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19. A device bonded on a reverse side thereof to one side of a double-sided adhesive sheet, the adhesive sheet comprising a grip tab which projects beyond one end of the device, the adhesive sheet being capable of being released from a substrate to which it is bonded by grasping the grip tab and pulling on the grip tab in a direction of a plane of a bond formed between said adhesive sheet and said substrate, and the device, on at least one end thereof, not abutting the adhesive sheet, but being offset therefrom a distance V, wherein the reverse side comprises a region separated by the distance V from the adhesive sheet.

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20. The device as claimed in claim 19, wherein the distance V is 0.1-1.5 mm.

21. The device as claimed in claim 20, wherein the distance V is 0.2-1 mm.

22. The device as claimed in claim 19, wherein the distance V ascends toward an edge over which the grip tab extends.

23. The device as claimed in claim 22, wherein the distance V rises continuously or discontinuously in steps.

24. The device as claimed in claim 22, wherein the distance V rises continuously to an angle  $\alpha$  of  $5^\circ$  -  $120^\circ$  between the region and the grip tab.

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25. The device as claimed in claim 24, wherein the angle  $\alpha$  is  $10^\circ - 90^\circ$ .
26. The device as claimed in claim 19, wherein the region has a breadth, depth W, which is equal to or greater than at least that of the adhesive sheet and wherein the region measures 1-20 mm in its depth W.
27. The device as claimed in claim 26, wherein the region measures 2-12 mm in its depth W.
28. The device as claimed in claim 19, wherein the region is roughened having an average roughness  $R_a$  of  $0.4 - 25 \mu\text{m}$ .
29. The device as claimed in claim 28, wherein the average roughness  $R_a$  is  $2 - 20 \mu\text{m}$ .
30. The device as claimed in claim 28, wherein the region has an average depth of roughness  $R_z$  of  $1-150 \mu\text{m}$ .
31. The device as claimed in claim 30, wherein the average depth of roughness  $R_z$  of  $2 - 100 \mu\text{m}$ .

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32. The device as claimed in claim 28, wherein the region is reduced together with the device by injection molding.

33. The device as claimed in claim 28, wherein the region is produced in a subsequent workstep selected from the group consisting of etching, grinding, embossing and spark erosion.

34. The device as claimed in claim 19, wherein the region comprises edges on which the adhesive sheet is capable of adhering with the grip tab projecting beyond the edges, and a distance V between the region and the adhesive sheet.

35. The device as claimed in claim 19, further comprising spacers whose height is less than a thickness of the adhesive sheet.

36. The device as claimed in claim 22, wherein the edge has a low static friction and sliding friction.

37. The device as claimed in claim 36, wherein the edge is a low-energy polymer surface.

38. The device as claimed in claim 19, wherein the adhesive sheet is elastically or plastically extensible with or without a carrier in between.

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39. The device as claimed in claim 19, wherein the adhesive sheet exhibits an adhesion less than its cohesion, the adhesion largely disappears when the adhesive sheet is extended, and the adhesive sheet exhibits a ratio of peel force to tear load of at least 1.2.0, and the adhesive sheet being based on thermoplastic rubber and tackifying resins, and exhibits high elasticity and low plasticity.

40. The device as claimed in claim 19, wherein the region is lined with a release laminate.

41. The device as claimed in claim 40, wherein the release laminate is a siliconized release paper or a release film.

42. The device as claimed in claim 19, further comprising fixing means located on its front face and/or lateral face.

43. The device as claimed in claim 42, wherein the fixing means are hooks or latching projections.

44. A method of adhering and releasing a device to a substrate, the method comprising the following steps:

a) providing a device according to claim 19;